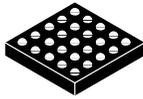


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



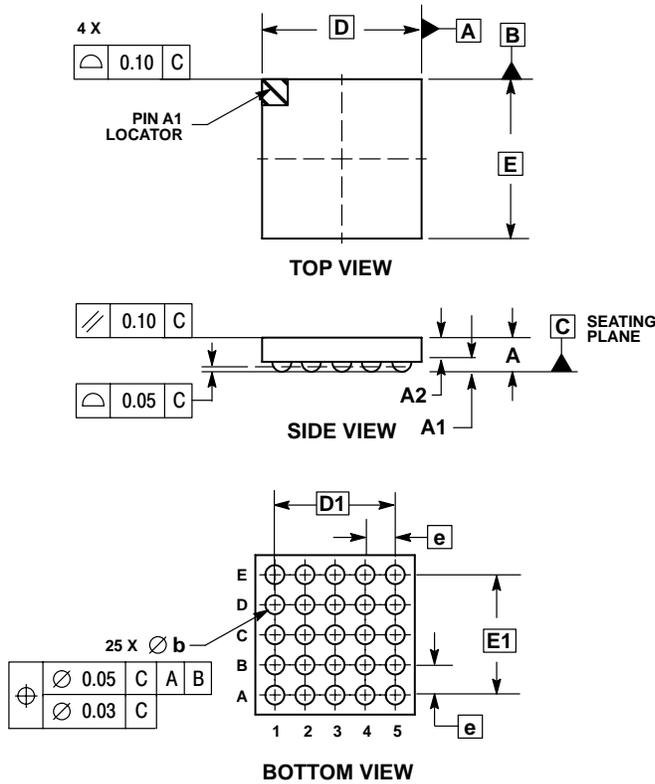
A1

SCALE 4:1

### FLIP-CHIP-25 CSP

CASE 499G-01  
ISSUE B

DATE 03 MAY 2005



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	2.650 BSC	
E	2.650 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	2.000 BSC	
E1	2.000 BSC	

### GENERIC MARKING DIAGRAM\*



xxxxxx = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	FLIP-CHIP-25 CSP, 0.265 *0.265 MM, 0.500 PITCH	PAGE 1 OF 2

